

Quad two-input NAND gate

54F00

ORDERING INFORMATION

DESCRIPTION	ORDER CODE	PACKAGE DESIGNATOR*
14-Pin Ceramic DIP	54F00/BCA	GDIP1-T14
14-Pin Ceramic Flat Pack	54F00/BDA	GDFP1-F14
20-Pin Ceramic LLCC	54F00/B2A	CQCC2-N20

* MIL-STD 1835 or Appendix A of 1995 Military Data Handbook

ABSOLUTE MAXIMUM RATINGS

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER	RATING	UNIT
V_{CC}	Supply voltage range	-0.5 to +7.0	V
V_I	Input voltage range	-0.5 to +7.0	V
I_I	Input current range	-30 to +5	mA
V_O	Voltage applied to output in High output state range	-0.5 to + V_{CC}	V
I_O	Current applied to output in Low output state	40	mA
T_{STG}	Storage temperature range	-65 to +150	°C

RECOMMENDED OPERATING CONDITIONS

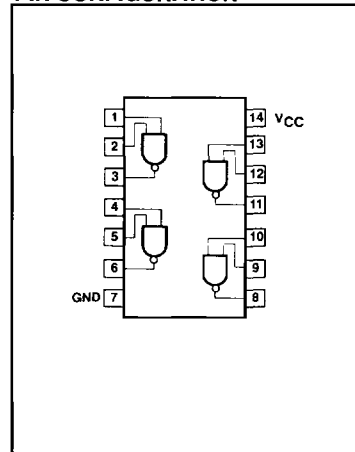
SYMBOL	PARAMETER	LIMITS			UNIT
		MIN	NOM	MAX	
V_{CC}	Supply voltage	4.5	5.0	5.5	V
V_{IH}	High-level input voltage	2.0			V
V_{IL}	Low-level input voltage			0.8	V
I_{IK}	Input clamp current			-18	mA
I_{OH}	High-level output current			-1	mA
I_{OL}	Low-level output current			20	mA
T_A	Operating free-air temperature range	-55		+125	°C

INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

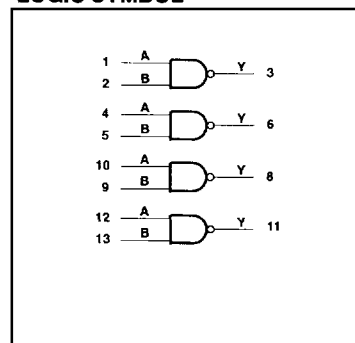
PINS	DESCRIPTION	54F(U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A, B	Inputs	1.0/1.0	20 μ A/0.6mA
\bar{Y}	Output	50/33	1.0mA/20mA

NOTE: One (1.0) FAST Unit Load (U.L.) is defined as: 20 μ A in the High state and 0.6mA in the Low state.

PIN CONFIGURATION



LOGIC SYMBOL



FUNCTION TABLE

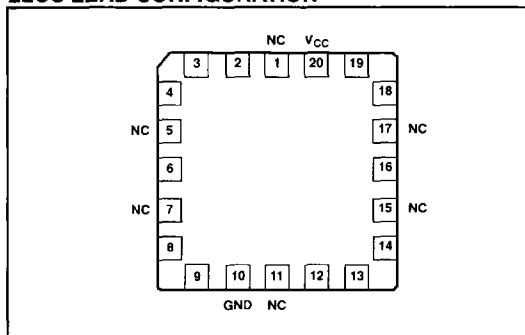
INPUTS		OUTPUT
A	B	\bar{Y}
L	L	H
L	H	H
H	L	H
H	H	L

H = High voltage level
L = Low voltage level

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LLCC LEAD CONFIGURATION



DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature unless otherwise noted.)

SYMBOL	PARAMETER	TEST CONDITIONS ¹	LIMITS			UNIT	
			MIN	TYP ²	MAX		
V _{OH}	High-level output voltage	V _{CC} = Min, V _{IL} = Max, I _{OH} = Max, V _{IH} = Min	2.5			V	
V _{OL}	Low-level output voltage	V _{CC} = Min, V _{IL} = Max, I _{OL} = Max, V _{IH} = Min		0.35	0.50	V	
V _{IK}	Input clamp voltage	V _{CC} = Min, I _I = I _{IK}		-0.73	-1.2	V	
I _{IH2}	Input current at maximum input voltage	V _{CC} = Max, V _I = 7.0V			100	μA	
I _{IH1}	High-level input current	V _{CC} = Max, V _I = 2.7V		1	20	μA	
I _{IL}	Low-level input current	V _{CC} = Max, V _I = 0.5V		-0.4	-0.6	mA	
I _{OS}	Short-circuit output current ³	V _{CC} = Max, V _O = 0.0V	-60	-80	-150	mA	
I _{CC}	Supply current (total)	V _{CC} = Max		V _I = GND	1.9	2.8	mA
				V _I ≥ 4.0V	6.8	10.2	mA

AC ELECTRICAL CHARACTERISTICS

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS					UNIT
			T _A = +25°C, V _{CC} = +5.0V C _L = 50pF R _L = 500Ω			T _A = -55°C to +125°C V _{CC} = +5.0V ± 10% C _L = 50pF, R _L = 500Ω		
			MIN	TYP	MAX	MIN	MAX	
t _{PLH}	Propagation delay A, B to Y	Waveform 1	2.4	3.7	5.0	2.0	7.0	ns
t _{PHL}			2.0	3.2	4.3	1.2	6.5	ns

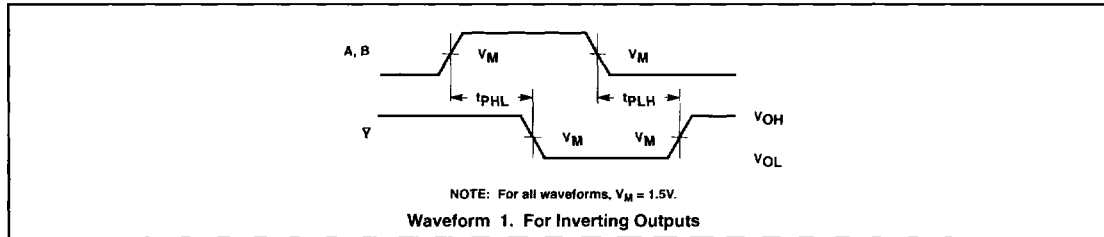
NOTES:

- For conditions shown as Min or Max, use the appropriate value specified under recommended operating conditions for the applicable type and function table for operating mode.
- All typical values are at V_{CC} = 5V, T_A = 25°C.
- Not more than one output should be shorted at a time. For testing I_{OS}, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

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AC WAVEFORMS



TEST CIRCUIT AND WAVEFORM

